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I Introduction

The primary objectives of this final report under JPL Contract No. 956778, Modification One are as follows:

- 1.) To develop a cost prediction model for various payload classes of instruments and experiments for the Space Shuttle Orbiter.
- 2.) To show the implications of various payload classes on the cost of:

Reliability Analysis

Quality Assurance

Environmental Design Requirements

Documentation

Parts Selection

Other Reliability Enhancing Activities

The model will have the following characteristics:

- * Predict Design / Development Costs (DDC)
- * Predict Hardware Costs (HUC1)
- * Show Results in FY 1984, \$, 10^6
- * Allow Manpower Level/Organizational Implications to be quantified
- * Utilize a Technology/Cost Class and Reliability Requirements Approach.
- * Use Standard cost modifiers such as:

I Introduction (cntd)

Technical risk factor
Development schedule factor
Inflation factor

* Introduce three new cost modifiers:

Yield in manufacturing
Yield in radiation hardness testing
Failure rate category number for parts
and assemblies

II Description of the Model

The payload classes are A, B , C, and D as defined in NMI 8010.1 and redefined in a form useful for this study in Reference 2.

The cost Model is based on two basic premises: (1) a building block approach is used ; and (2) a technology / cost class approach is used. In this way many combinations of technologies and cost classes can be utilized in costing new instrument systems using a building block data base rather than a sub-system ,data -base history which is usually unavailable. The technologies and cost classes are described in Tables 1 & 2.

The quantification of a cost amplifier, based on reliability requirements, is shown in Table 3 and is taken from Reference 1.

Since the central purpose of this new cost model is to show how the costs may vary with traditional reliability theory and activities, several new parameters have been introduced. These are : Reliability Enhancing Activities Factor, (REAF) and Allowable Failure Rate Factor (AFRF).

The development of REAF is shown in Tables 4 and 5 ; and the results , shown in Table 6, are shown to be a function of payload class only (ICN). Thus the manpower levels shown with each payload class lead to a very important cost driver; namely REAF .

The development of AFRF is shown in Tables 7 and 8 ; and the results , shown in Table 9 , are shown to be a function of Failure Rate Category Number (FRCN) only. Table 8 is presented primarily to assist in the selection of FRCN as required to

II (contd)

select AFRF from Table 9.

The cost estimating relationships (CERS) for DDC and HUC1 represent the data base for this model as taken from Reference 1 and updated in 1983. These CERS are shown in Tables 10 & 11.

The Hardware Cost Formula and the Design Development Cost Formula are shown in Tables 12& 13. These tables along with the data base CERS represent the backbone of this cost prediction model.

The standard cost modifiers are :

IHDF or TERF

INFN

DESF

SLAT and are presented in Tables 14 through 17.

The new cost modifiers are :

$Y_1 = Y_M$, Yield in manufacturing

$Y_2 = Y_{RH}$, " " radiation hardness testing

FRCN , Failure Rate Category Number

and are presented in Tables 8,9,12,& 13.

1.146 |

5

GLOSSARY OF TECHNOLOGIES AND COST CLASSES
TABLE /

T 3 Mechanical Devices

- CC1 Structure Airborne Steel, Aluminum Parts, Medium Precision, Covers, Frames, Plates, Light Plane Structure
- CC2 Gears, Bearings, Seals, Radomes, Spacecraft Mechanical Devices
- CC3 Gimbals and Platforms for IRU, and Radar Antennas, Medium Precision Gyros, Indexing or Articulated Head with Optical
- Path through Hinge Line, S/C - simple structure
- CC4 Extreme Precision Displacement and Rate Gyros, S/C shared chassis structure

T 4 Fluid Systems

- CC1 Commercial Class Hydraulics*, Lines, Filters, Simple Actuators
- CC2 Airborne or Spaceborne or Military Class Hydraulic* Cylinders, Actuators, Fluidics
- CC3 Airborne or Spaceborne or Military Class Special Hydraulic* Cylinders, Actuators, Accumulators
- CC4 Airborne or Spaceborne or Military Class Extreme Precision Hydraulics*, Three-Way Solenoid Valves, Two-Stage Electro-Hydraulic Servo Valves, Hydraulic Pumps, Motors

* Cold gas or pneumatics

GLOSSARY OF TECHNOLOGIES AND COST CLASSES

TABLE 2

T 1 Electrical/Electronics

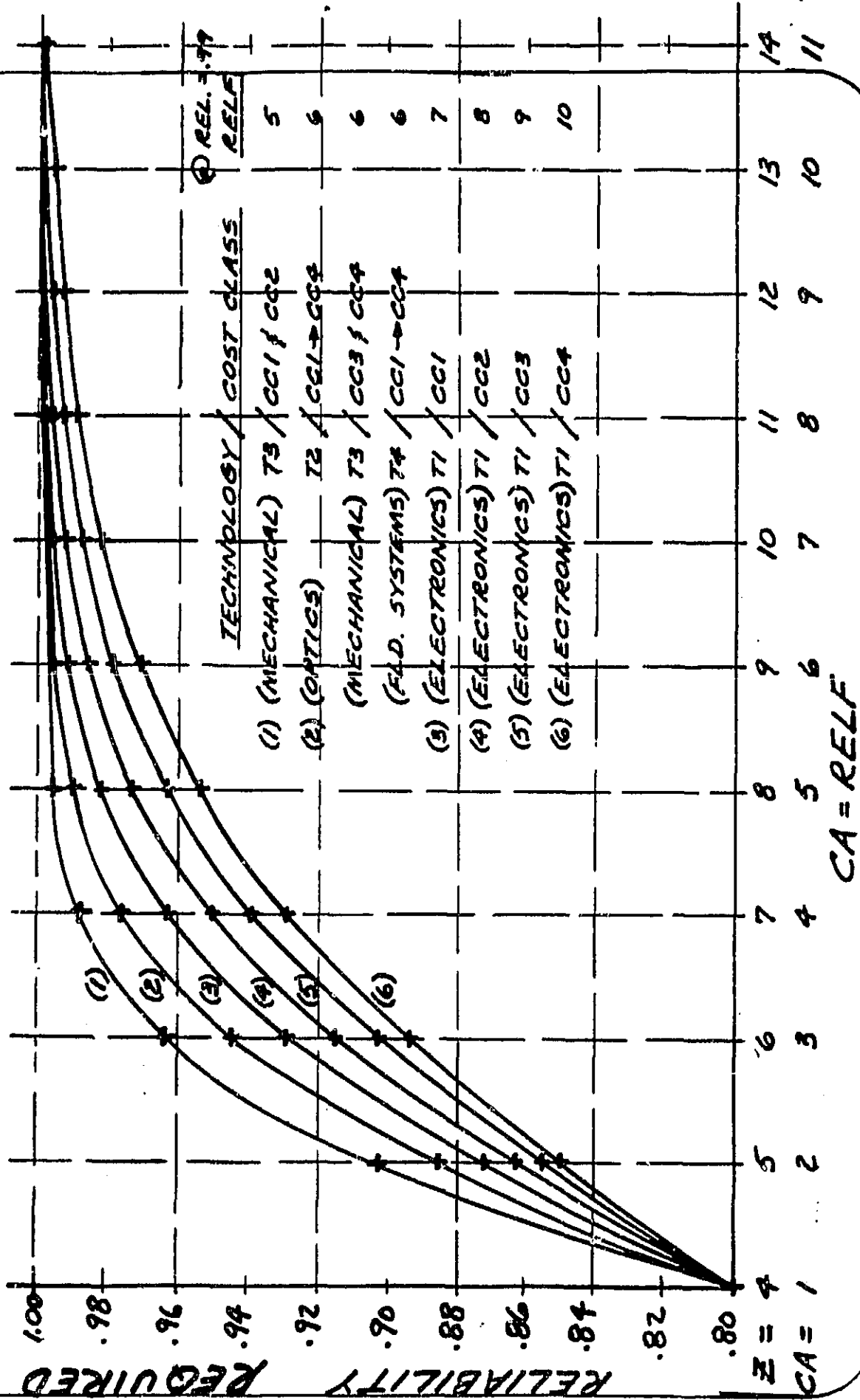
- CC1 Resistors, Capacitors, Coils, Switches, Cabling, Wiring Harness
- CC2 Microprocessors, Power Supplies, Airborne Displays, Electro-Mechanical Servos S/C Comms- geoc.
Controls, Resolver, PCB and Cards, Sensors, Batteries, Inverters, Small Electric Motors
- CC3 Vidicons, Accelerometers for IRU, TV Electronics, Video Pre-Amps, Data Handling,
Airborne Radar XB, Airborne Computers $\Psi = 1$; S/C Comms- planetary
- CC4 Airborne Radar KBD, Airborne Computers $\Psi = 8$

T 2 Optical Devices

- CC1 Lens, Prisms, Filters, Mirrors, Fiber Optics, Windows with Optics Requirements
- CC2 Telescopes, Optical Assemblies, Optical Sensors
- CC3 Lasers, Image Converters, Interferometer
- CC4 IRR, FLIRS

RELIABILITY VS. COST AMPLIFIER

TABLE 3



REAF DEVELOPMENT - PART ONE

TABLE 4

PAYLOAD CLASS

ITEM

i =

A

B

C

D

PROGRAM MGT
HDW (HUCI)
GSE
DDC
PRE-LAUNCH COST
TPC
(ESTIMATING BASE)

RELIABILITY ANALYSIS

QUALITY ASSURANCE

PARTS SELECTION

DOCUMENTATION

ENVIRONMENTAL DESIGN REQTS

OTHER

SUB-TOTAL

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$$Z = Z_0 / Z_A$$

Z

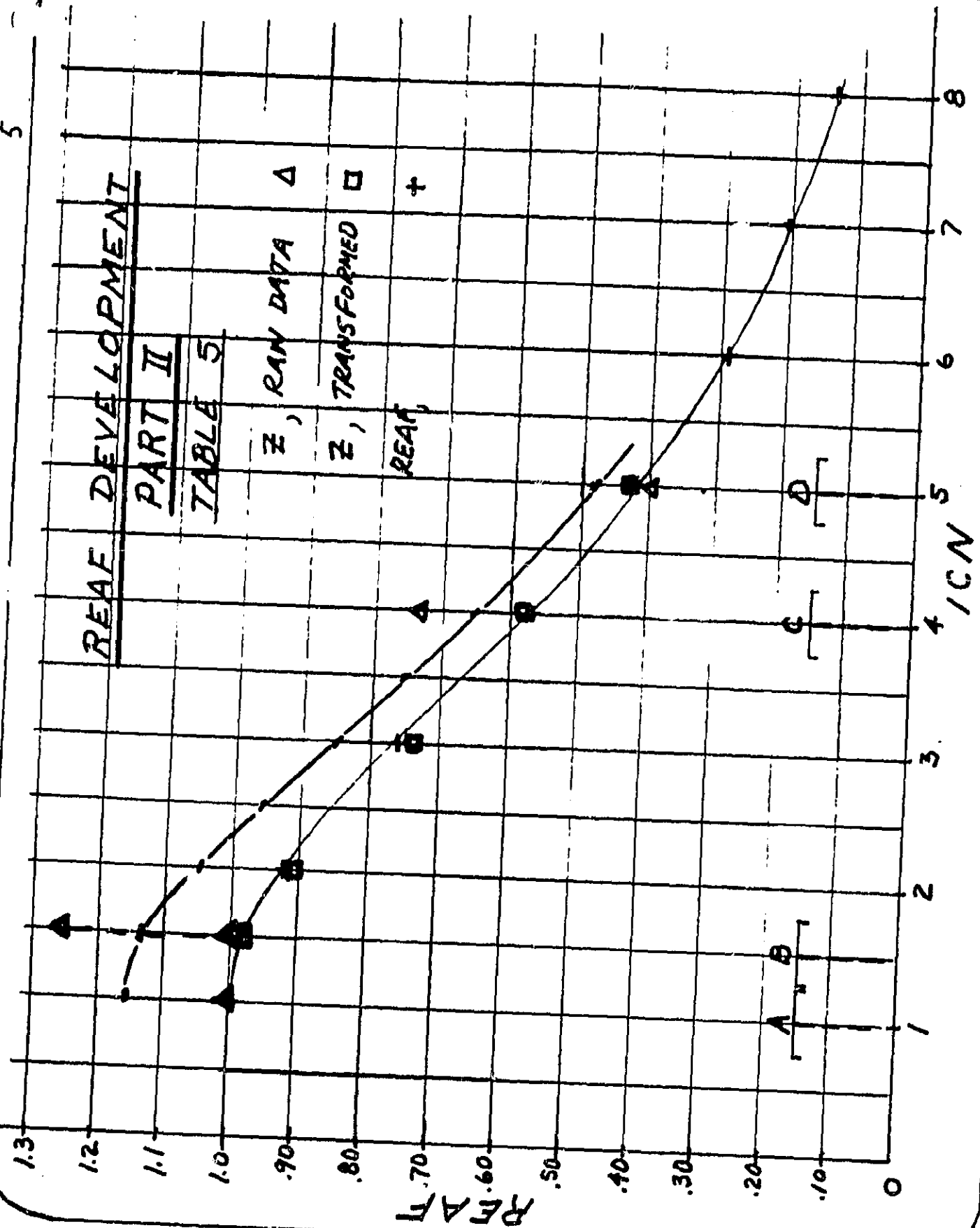
=

REAF DEVELOPMENT

PART II

TABLE 5

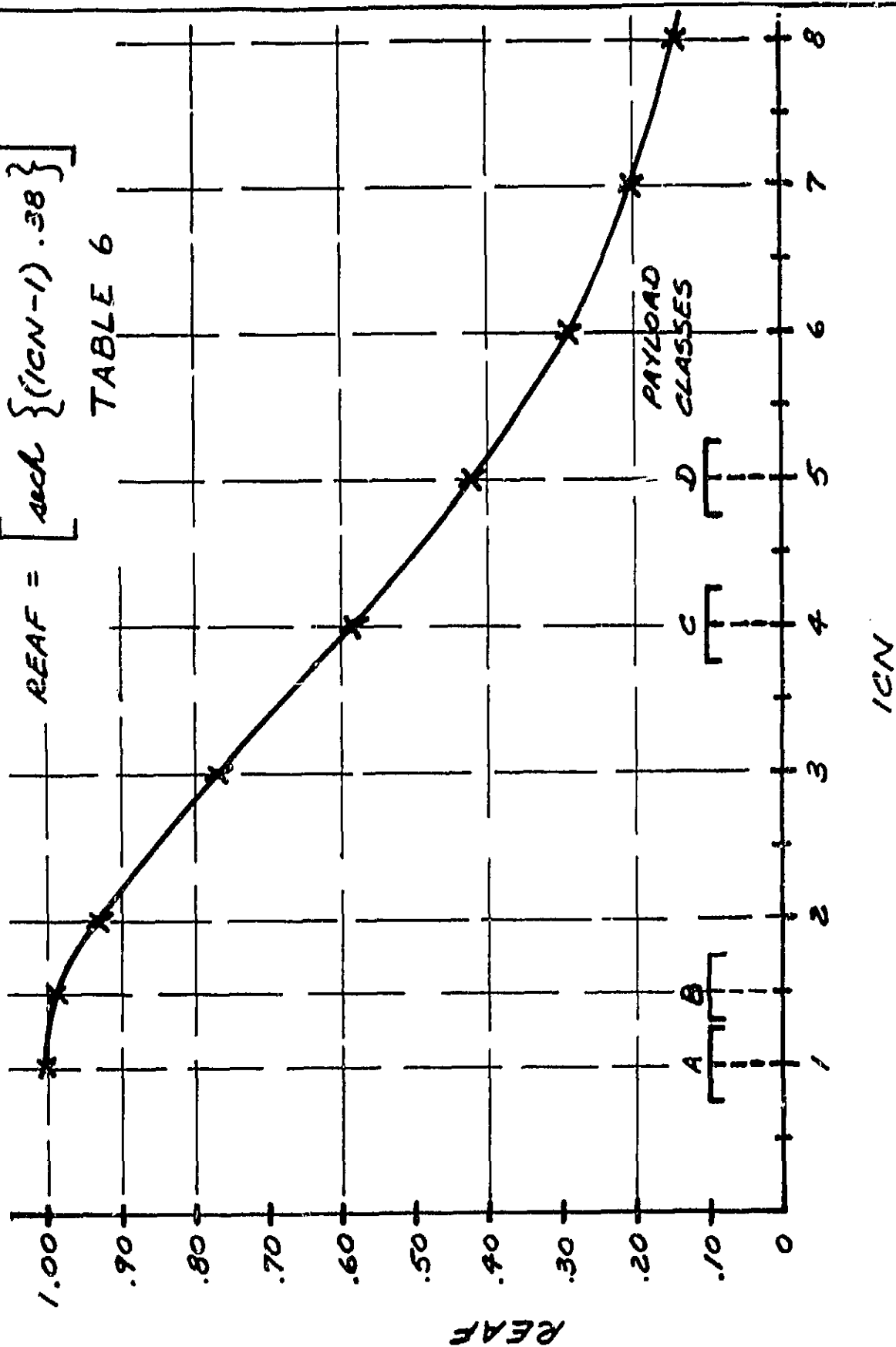
Δ Z, RAW DATA
 \square Z, TRANSFORMED
 $+$ REAF



RELIABILITY ENHANCING ACTIVITIES FACTOR

$$REAF = \left[\text{sech} \{ (ICN - 1) \cdot .38 \} \right]$$

TABLE 6



ICN

ALLOWABLE FAILURE RATESANDCATEGORIESTABLE 7

FREN	RELIABILITY REQTS	λt	t HRS	ALLOWABLE $\lambda/10^6$ HRS	
1	.988	.012073	900	13.4	
		.012073	300	40.2	
2	.98	.020203	900	22.4	
		.020203	300	67.3	
3	.96	.040822	600	68.0	
		.040822	200	204.1	
4	.94	.061875	600	103.1	
		.061875	200	309.4	
5	.92	.083382	210	397.1	
		.083382	70	1191.2	
6	.90	.105361	210	501.7	
		.105361	70	1505.2	

$$REL = e^{-\lambda t}$$

FAILURE RATE CATEGORY NUMBER

TABLE 8

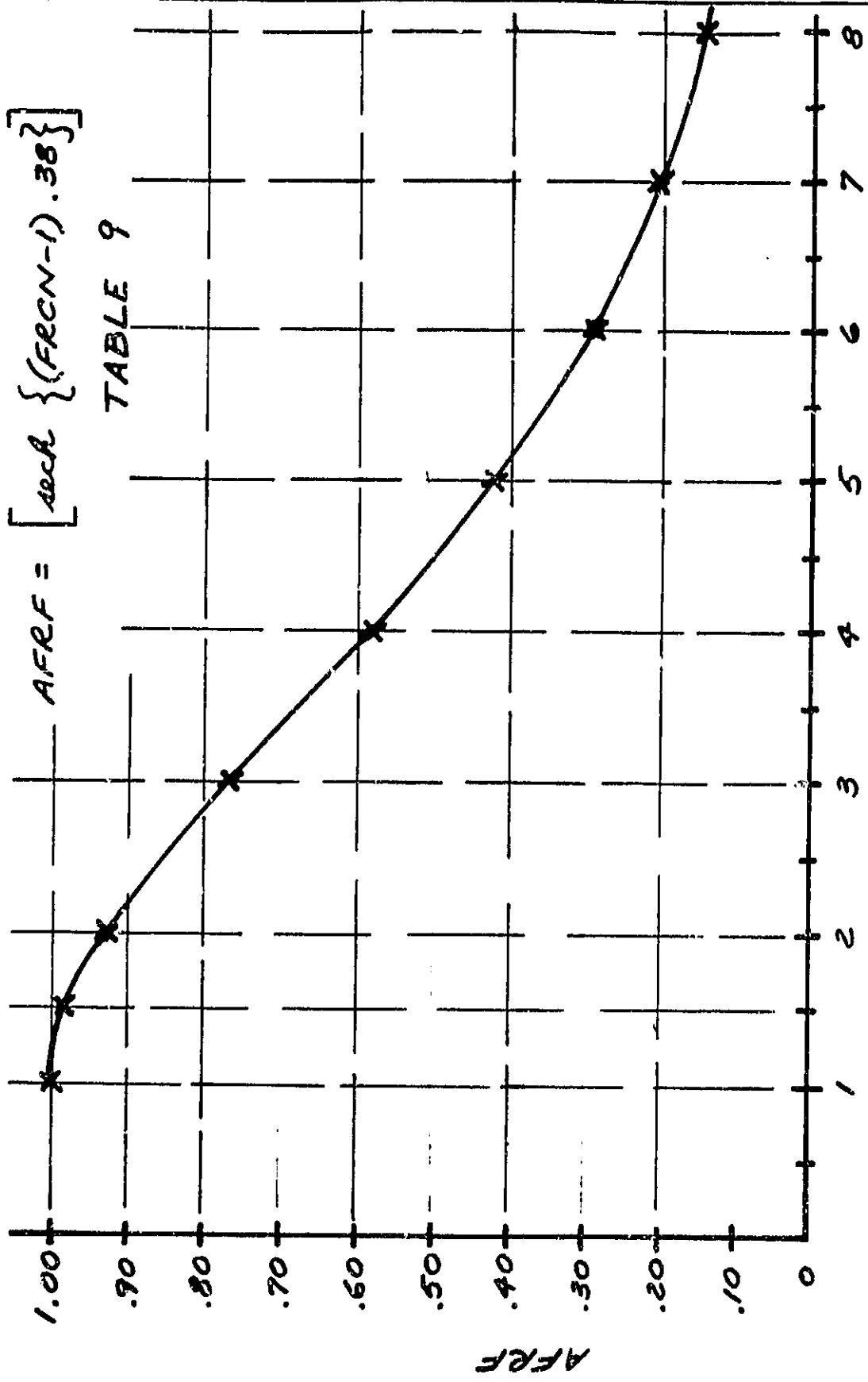
COMPONENT ALLOWABLE X RANGE ELECTRONIC PARTS SELECTION SPECS

1	10 40	JPL ZPP-2061 PPL White Sata JPL " " Blue Sata
2	20 70	MIL-570-975 Grade 1 " Grade 2
3	70 200	MIL-M-38510, Class 5 " " Class 8
4	100 300	MIL-S-19500, JANS " " JANXXV
5	300 1200	Commercial
6	800 1500	Commercial

✓ ALLOWABLE FAILURE RATE FACTOR

$$AFRF = \left[secA \{ (FRCN-1) \cdot 38 \} \right]$$

TABLE 9



TECHNOLOGY/
Cost Class

10^{b1}

b1

HUC1
FORMULA

F1

HUC1
@W= 100

MC

a1

T1	<u>ELECTRONICS</u>					
11	CC1	4.0	0.602060	.000743	10	.011888
12	CC2	4.0	0.602060	.002970	10	.04752
13	CC3	4.0	0.602060	.005940	10	.09504
14	CC4	4.0	0.602060	.011880	10	.19008

T2	<u>OPTICAL DEVICES</u>					
21	CC1	4.0	0.602060	.001069	20	.017104
22	CC2	4.0	0.602060	.004277	20	.068432
23	CC3	4.0	0.602060	.008554	20	.136864
24	CC4	4.0	0.602060	.034214	20	.547424

T3	<u>MECHANICAL</u>					
31	CC1	4.0	0.602060	.000267	10	.004272
32	CC2	4.0	0.602060	.000535	10	.00856
33	CC3	4.0	0.602060	.002138	10	.034208
34	CC4	4.0	0.602060	.006415	10	.10264

T4	<u>FLUID SYSTEMS</u>					
41	CC1	4.0	0.602060	.000119	20	.001904
42	CC2	4.0	0.602060	.000238	20	.003808
43	CC3	4.0	0.602060	.00475	20	.007600
44	CC4	4.0	0.602060	.001901	20	.030416

$$HUC1 = y = a_1 w^{b1} = [HUC1] \left[\frac{1}{4 \text{ MOD}} \right]$$

Table 11

TCCM: DDC CERS

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OF POOR QUALITY

15

COLUMN
WRITE 6TECHNOLOGY/
Cost Class 10^{b_2} b_2

DDC FORMULA

 a_2 F_2 DDC
@ W=100

1	MC						
2	T1	<u>ELECTRONICS</u>					
3	15	CC1	2.0	0.301030	.0564	1.80	.2256
4	16	CC2	2.0	0.301030	.2257	1.80	.9028
5	17	CC3	2.0	0.301030	.4515	1.80	1.806
6	18	CC4	2.0	0.301030	.9029	1.80	3.6116
7	T2	<u>OPTICAL DEVICES</u>					
8	25	CC1	2.0	0.301030	.0832	1.50	.3328
9	26	CC2	2.0	0.301030	.3327	1.50	1.3308
10	27	CC3	2.0	0.301030	.6653	1.50	2.6612
11	28	CC4	2.0	0.301030	2.6611	1.50	10.6444
12	T3	<u>MECHANICAL</u>					
13	35	CC1	2.0	0.301030	.0446	1.00	.1784
14	36	CC2	2.0	0.301030	.0891	1.00	.3564
15	37	CC3	2.0	0.301030	.3564	1.00	1.4256
16	38	CC4	2.0	0.301030	1.0692	1.00	4.2768
17							
18	T4	<u>FLUID SYSTEMS</u>					
19	45	CC1	2.0	0.301030	.0178	1.00	.0712
20	46	CC2	2.0	0.301030	.0357	1.00	.1428
21	47	CC3	2.0	0.301030	.0713	1.00	.2852
22	48	CC4	2.0	0.301030	.2851	1.00	1.1404
23							
24							
25							
26							
27							
28							
29							
30							
31							
32							
33							
34							
35							
36							
37							
38							
39							
40							

$$DDC = y = a_2 \cdot 10^{b_2} = [DDC]_{W=100} \left[\frac{1}{2^{NOD}} \right]$$

HARDWARE FIRST UNIT COST

$$\Delta HUCI = RELF^m (REAF)^m (AFRF)^2$$

WHERE: $NOD = \log_{10} \frac{100}{W}$

$$n = d \cdot \text{sch} \{ (1cN-1) \varphi \}$$

$$d = 1.1575$$

52. 11 f

7935

$$LFI = \frac{2}{e^{+(NOD)A_1} + 1}$$

$$R_1 = 0.70 \quad 0.946 ; \quad USE \quad 0.473$$

TERF = TECHNICAL RISK FACTOR: SEE PAGES 4

$$TI = CBI(SLAT)(INFN)(Y_M)(Y_{RH})(TERF.^{.15})$$

$$SLAT = 1 + .40(.90)^{NOFA}$$

NOFA = NO. OF FLIGHT ARTICLES

TABLE 12

$$cBCI = 1.00$$

$$Y_M = \text{YIELD MANUFACTURING}$$

$$Y_{RH} = \text{YIELD RADIATION HARDNESS}$$

$$\alpha = 1.1194 \left(\frac{q}{cc} \right)^{.548}$$

$$CC_i = 1 \text{ FOR COMPONENTS } 2, 3, \text{ OR}$$

= 4 FOR ASSEMBLIES :
SELECT ONE

DESIGN/DEVELOPMENT COST

$$\Delta DDC = RELF^A (REAF)^L (AFRF)^B \left[DDC \right]_{W100} \left[\frac{1}{2^{NOD}} \right] (LF2) (T2)$$

TABLE 13

WHERE:

$$NOD = \log_{10} \frac{100}{W} \quad CBC2 = 1.00$$

$$k = g \text{ such } \{(1, N-1) k\}$$

1936/11/2

33.3

$\frac{1}{2} = .7935$

$$LF2 = \frac{2}{e^{(MOD)A2} + 1}$$

$$L_2 = 0.70 \quad 0.624 ; \quad USE \quad 0.512$$

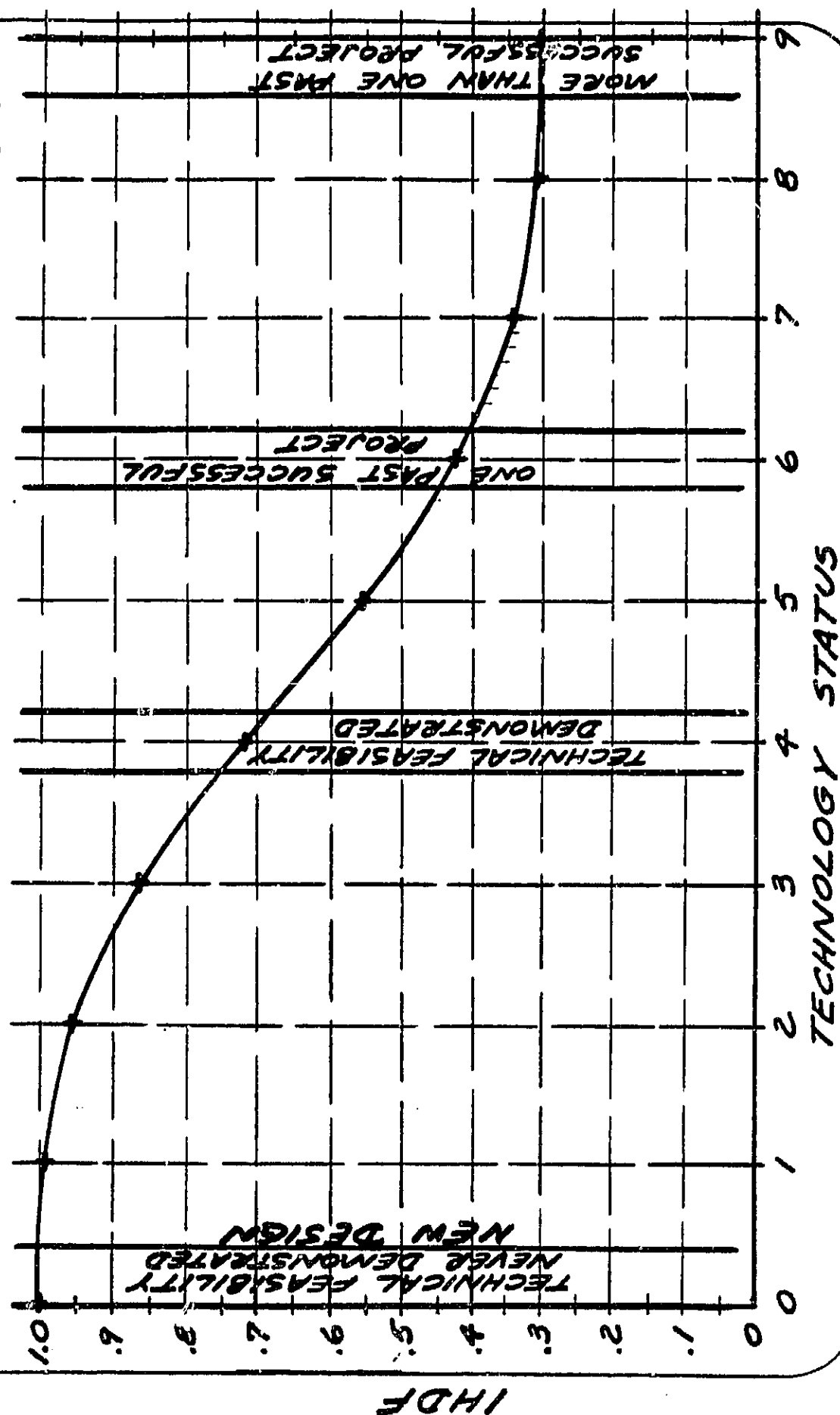
TERF = TECHNICAL RISK FACTOR : SEE PAGES _____

T2 = C8C2 (DEF) (INF) (DOMAIN FACTOR) (TERF)

DESF = DEVELOPMENT SCHEDULE FACTOR : SEE PAGE

INHERITED DEVELOPMENT FACTOR (IHDF) VS. TECHNOLOGY STATUS

TABLE 14



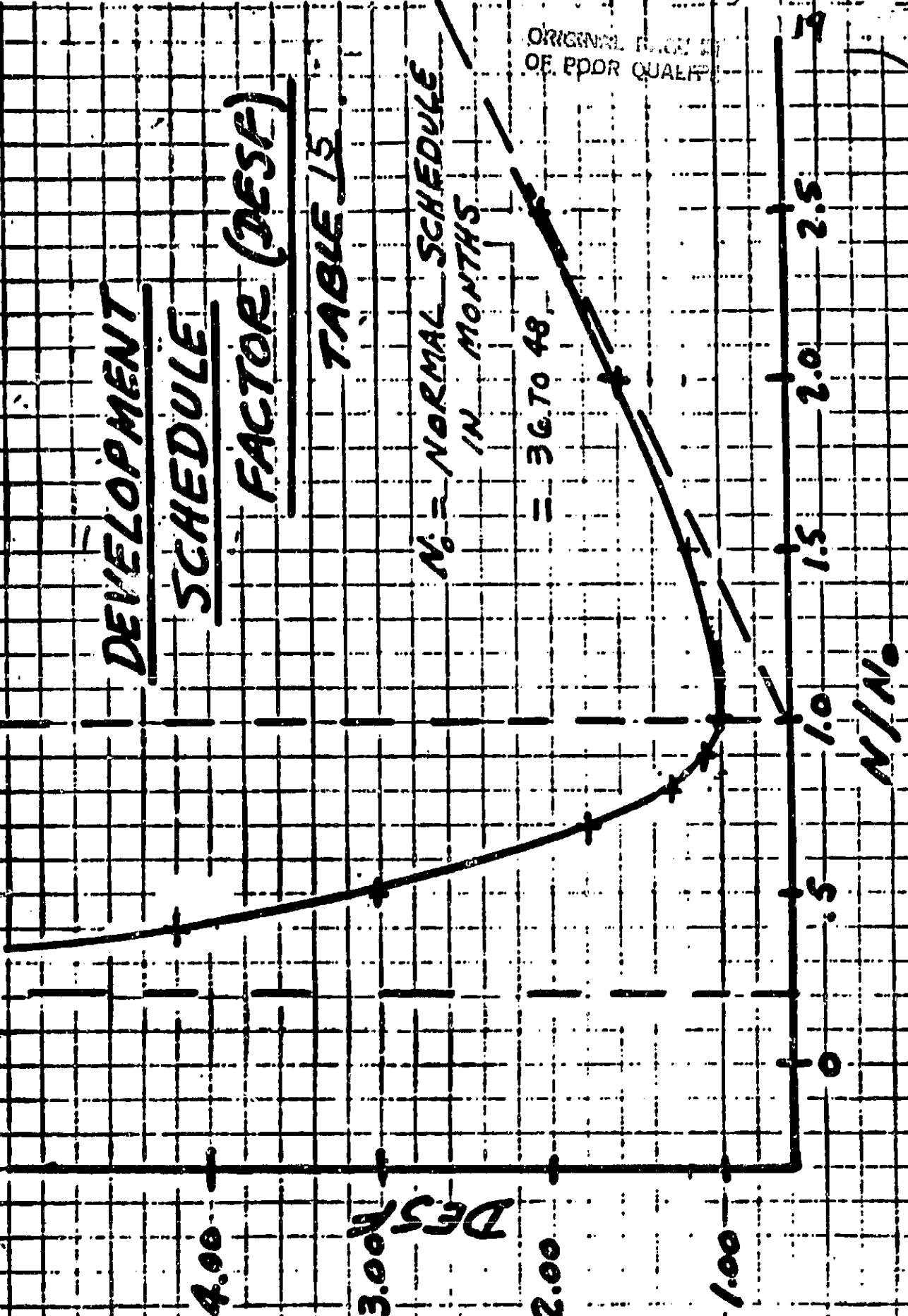
DEVELOPMENT SCHEDULE FACTOR (DES)

TABLE 15

N_0 = NORMAL SCHEDULE
IN MONTHS

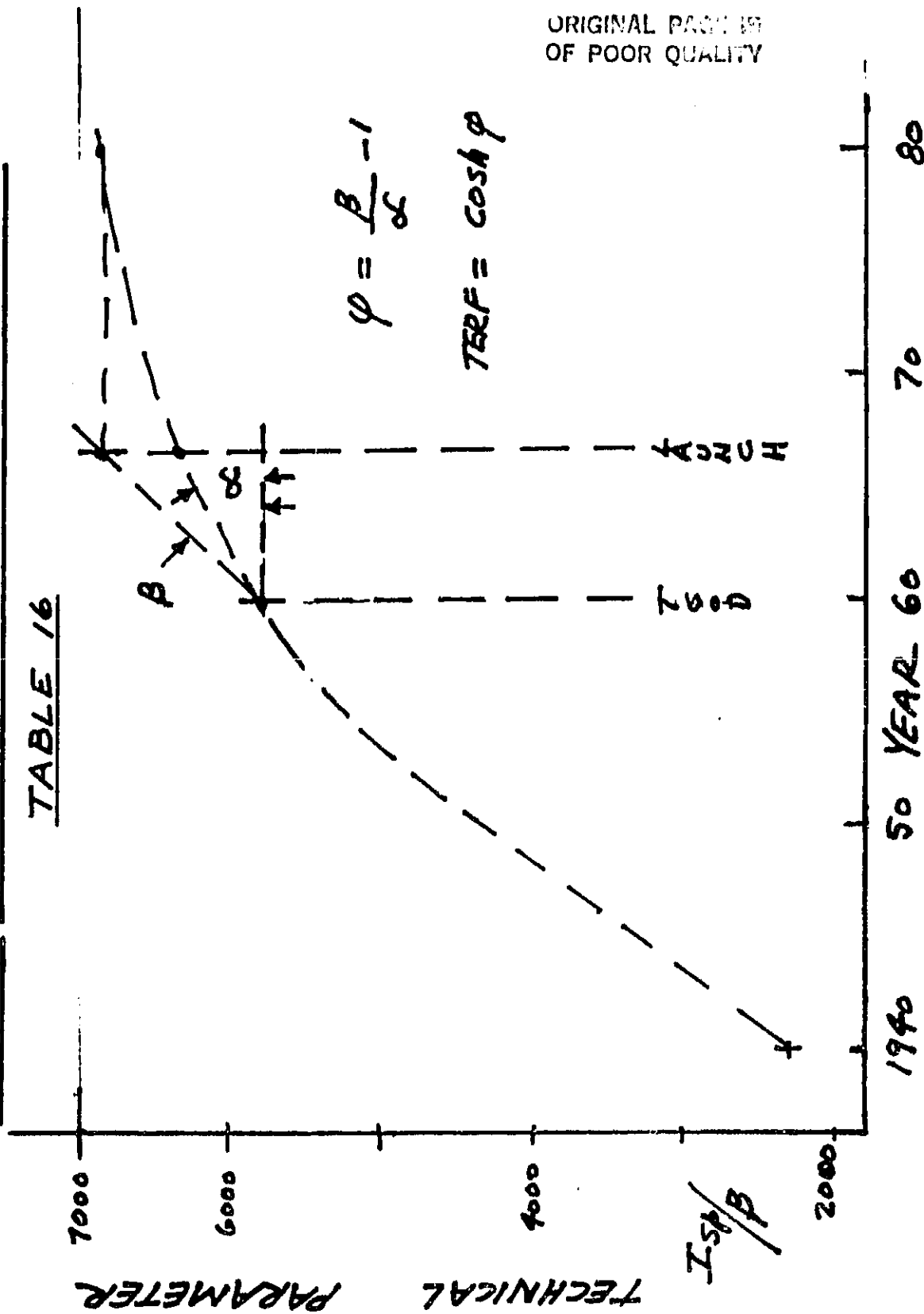
= 36 TO 48

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TECHNICAL RISK FOR ROCKET STAGES

TABLE 16



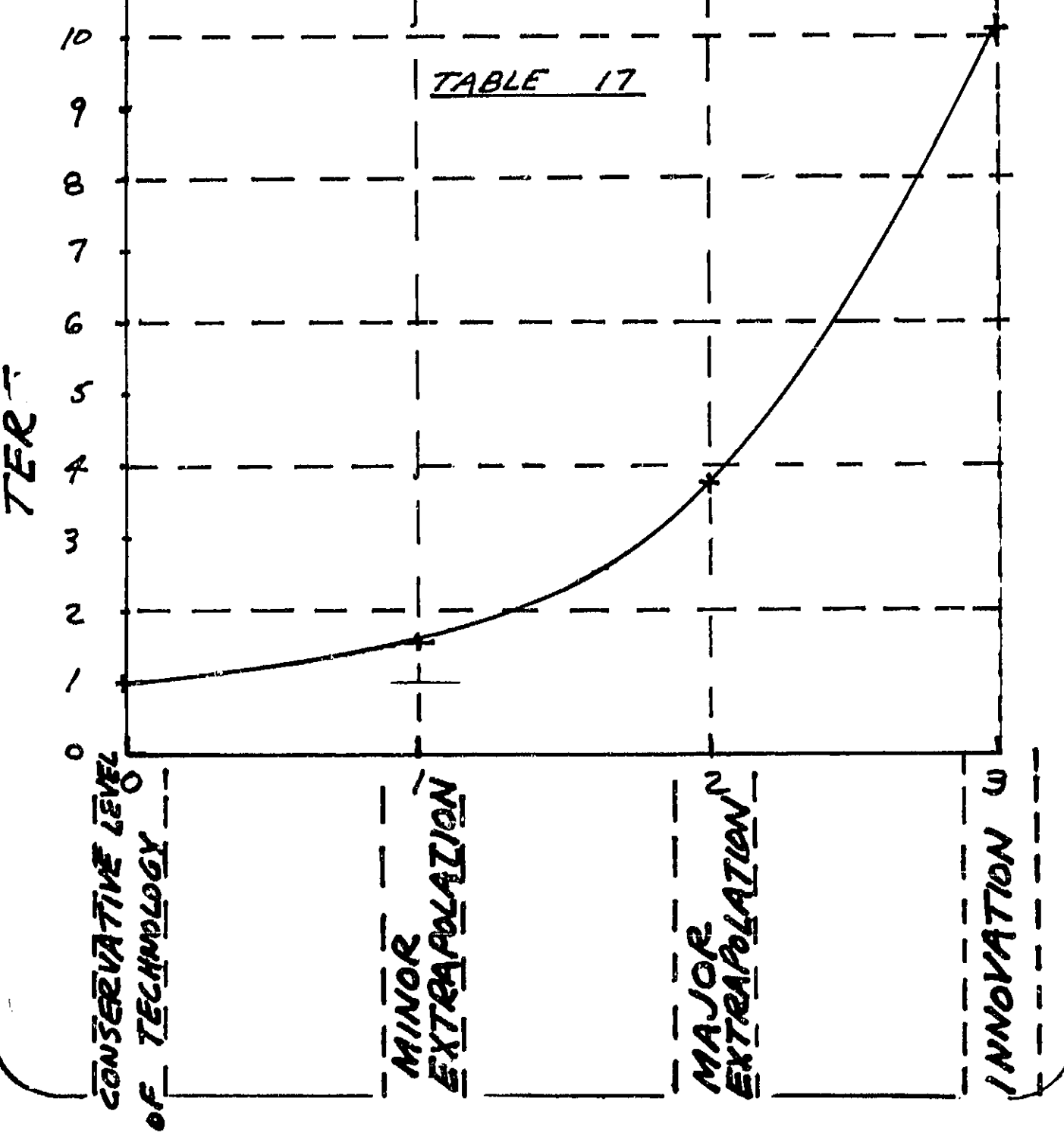
FEMA
9/15/79

21

REV. A 10/26/79

TERF - SHORT FORM

IF INSUFFICIENT TECHNICAL DATA ARE AVAILABLE TO CONSTRUCT A PLOT SUCH AS SHOWN ON PAGE 34 USE THIS FORM.



III Illustration of the Model

The cost model is illustrated by showing the detailed input calculations and the results for a previous design (VOIR III) of a Venus Mapping Radar in Tables 18 19 & 25.

VENUS MAPPING RADAR

TABLE 18

	(101)	(102)	REF/APRF	(103)	(104)	(105)
	(lbs)	TICC	REL	[HUC I] W 100	[DDC] W 100	TERF W 100
ANTENNA	2.47	M33,37	6	10/1.0	.034208	1.4256
TRANSMITTER	57	E13,17	9		.09504	1.806
	20	E14,18	10		.19028	3.6116
RECEIVER	19	E13,17	9		.09504	1.806
	10	E14,18	10		.19028	3.6116
CONTROL/LOGIC	11	E12,16	8		.04752	.9028
POWER MODULE	53	E12,16	8		.04752	.9028
DATA HDLG	18	E13,17	9		.09504	1.806
HOUSING	66	M32,36	5		.00856	.3564
RF CABLE	22	E11,15	7		.011888	.2256
[523] lbs						
CLASS A	/ FRCN = 1.0					
ICN = 1						
MODEL	HUC I 5.175 DDC 19.271					
ACTUAL	-					

\$, 10⁶

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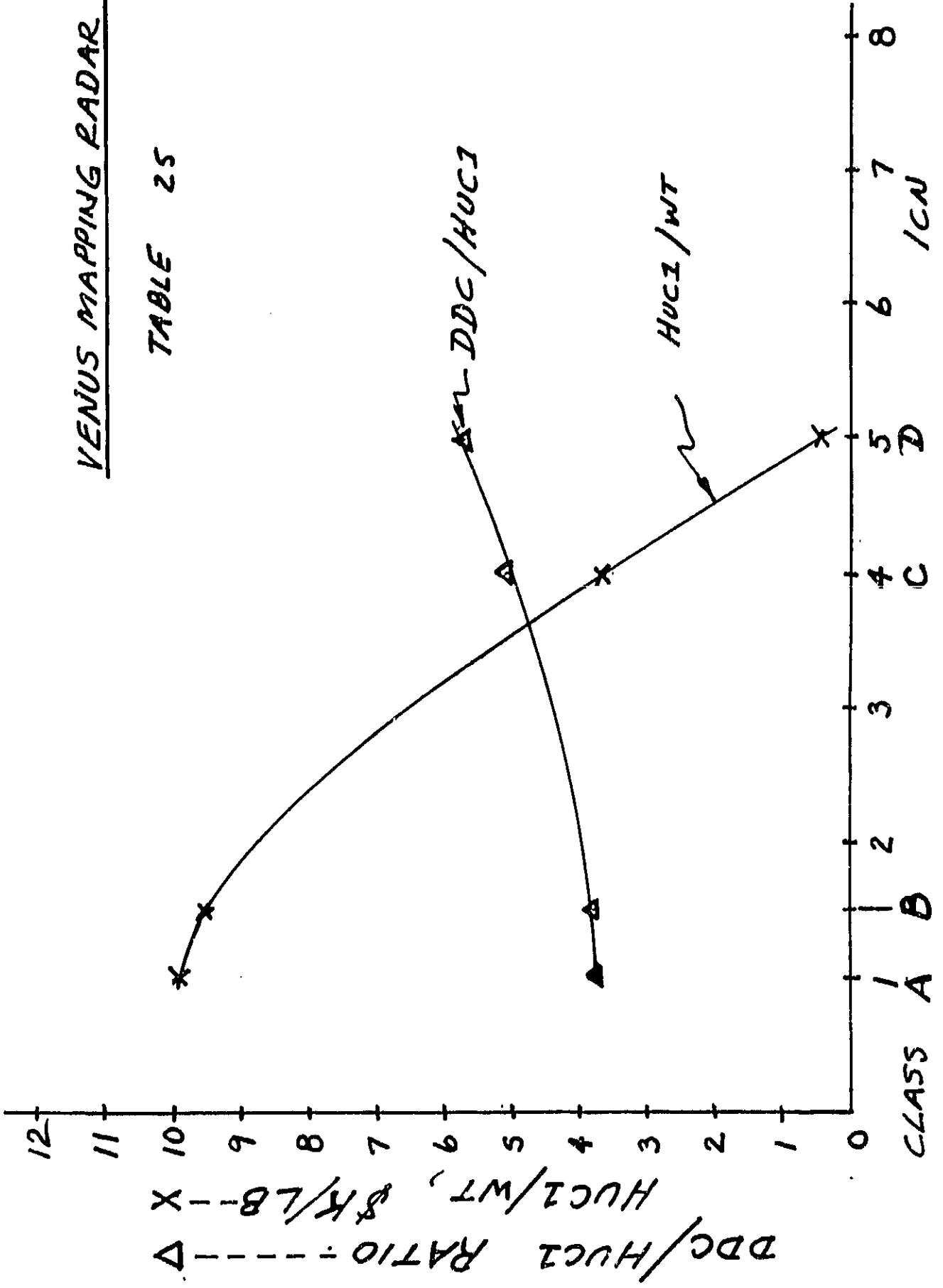
VENUS MAPPING RADAR

	1	2	3	4
CLASS	A	B	C	D
1 ICN	1	1.5	4	5
2 EFCN	1	1	1	1
3				
4 COST SUMMARY:				
5				
6 HUC1	5.175	5.003	1.903	1.064
7				
8				
9 DDC	19.271	18.811	9.735	6.080
10				
11				
12 \$/LB	9895	9566	3639	2034
13				
14				
15 DDC/HUC1	3.724	3.760	5.116	5.714
16				
17				
18				
19				
20				
21				
22				
23				
24				
25				
26				
27				
28				
29				
30				
31				
32 WT. = 523 lbs				
33				
34				
35				
36				
37				
38				
39				
40				

VENUS MAPPING RADAR

TABLE 25

25



IV Discussion of the Results

Cost summary results are shown in Tables 20 through 24 for the following Shuttle Orbiter payloads :

Galileo Imaging S.S.

Atmos

SIR-B

Super Fluid Helium

DDM

PROGRAM : GALILEO IMAGING SS.

CLASS : A ; ICN = 1 ; WT = 65.4285

COMPONENTS : JPL-2PP-2061 PPL ; FREN = 1
WAVE SLITS 29.7 Kg

CO_i = 4

	<u>HUC1</u> \$, 10 ⁶	<u>DDC</u> \$, 10 ⁶
MODEL	2.050	17.235
ACTUALS	3.296	14.993

MODEL

ACTUALS

PROGRAM : ATMOS

CLASS : C

; ICN = 4

; WT = 541 LBS

COMPONENTS: MIL-M-38150

; FRCN = 3

245 Kg

CLASS S

CG_i = 3

	$\frac{HUCI}{\$, 10^6}$	$\frac{DDC}{\$, 10^6}$
MODEL	1.970	14.615
ACTUALS	2.538	15.212

PROGRAM : SIR-B

CLASS : C

WT = $\frac{1120}{105}$
508 kg

ICN = 4

COMPONENTS: MIL-STD-97S
GR 2

FREN = 2

CO₂ = 4

<u>HUCI</u>	<u>\$₁</u>	<u>DDC</u>
3.491		10,947
4.250		10,533

MODEL

ACTUALS

PROGRAM : SUPER FLUID HELIUM

CLASS : C ; ICN = 4 ; WT = 576 LOS

COMPONENTS : COMML ; FRCN = 5 262 Kg

CC_i = 4

CLASS	HUCI \$, 10 ⁶	DDC \$, 10 ⁶
C ⁺	0.501	5.204
C	0.267	2.856
D	0.154	1.983
ACTUALS	.900	3.111



PROGRAM : DDM

CLASS : C ; ICN = 4 ; WT = 728 LBS

COMPONENTS: Comm ; FRCN = 5 330 Kg

CC_i = 4

	$\frac{HUCI}{\$, 10^6}$	$\frac{DDC}{\$, 10^6}$
MODEL	0.463	4.066
ACTUALS	UNKNOWN	UNKNOWN

V References

1. Hoffman, F. E. ; "Development of the JPL Cost Prediction Model for Shuttleborne Instruments"; FEHA Report No. 79-06-01 ; dtd July 18, 1979.
2. Gibberson, W. E. ; " FPO- Payload Classification Product Assurance Provisions" ; JPL D-1489 and FPO 600-3 ; dtd April 17, 1984.

Appendix I Glossary

HUC1	, Hardware First Unit Cost
DDC	, Design/ Development Cost
IHDF	, Inherited Development Factor
TERF	, Technical Risk Factor
INFN	, Inflation Factor
Y_1	, Yield due to manufacturing
Y_2	, " " " radiation hardness testing
RELF	, Cost Amplifier due to technology and reliability requirements
DESF	, Development Schedule Factor
REAF	, Reliability Enhancing Activities Factor
AFRF	, Allowable Failure Rate Factor
ICN	, Instrument Class Number
FRCN	, Failure Rate Category Number
CC_1	, Cost Class for assemblies or Components
λ	, Component failure rate per million (10^6) hours

INPUT FORM BLANK

CPM FOR SHUTTLE
INSTRUMENTS

DATA STRING INPUTS :

REGISTER

GENERAL :

WT	01
REF	02
[HUC1] WIM	03
[DDC] W100	04
TERF(OR IHDF)	05

ICN	Input	51
FRCN	" Reference only	
REAF	ICN & Table	06
AFRE	FRCN & Table	07
DESE	Input	08
INEN	"	09
Domain Factor		10

HUC1

CO _i		50
n	Calc.	52
m	Input	53
K1	"	54
NOFA	"	
$1 + .40(.90)^{NOFA} =$	SLAT Calc. &	56
	CBC1 Input	57
HT = Δ =	T1 Calc. &	20
	a Calc.	55

DDC

b	Input	30
k	Calc. &	32
h	Input	33
K2	"	34
CBC2	"	35
DT = Δ =	T2 Calc. &	28

YIELD _{WFG}	Input	44
YIELD _{RAD HD.}	"	45